



# BAP64-04W

Silicon PIN diode

Rev. 4.1 — 11 February 2019

Product data sheet

## 1 Product profile

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### 1.1 General description

Two planar PIN diodes in series configuration in a SOT323 small SMD plastic package.

### 1.2 Features and benefits

- High voltage, current controlled
- RF resistor for RF attenuators and switches
- Low diode capacitance
- Low diode forward resistance
- Low series inductance
- or applications up to 3 GHz
- AEC-Q101 qualified

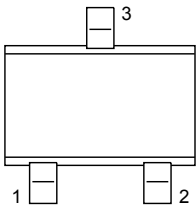
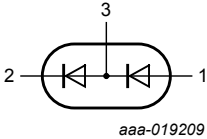
### 1.3 Applications

- RF attenuators and switches



## 2 Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Graphic symbol
1	anode	 <p>Top view</p>	 <p>aaa-019209</p>
2	cathode		
3	common connection		

## 3 Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BAP64-04W	-	plastic surface-mounted package; 3 leads	SOT323

## 4 Marking

Table 3. Marking code

Type number	Marking code
BAP64-04W	4W%

## 5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_R$	continuous reverse voltage		-	100	V
$I_F$	continuous forward current		-	100	mA
$P_{tot}$	total power dissipation	$T_{sp} \leq 90\text{ °C}$	-	240	mW
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-65	+150	°C

## 6 Thermal characteristics

**Table 5. Thermal characteristics**

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		250	K/W

## 7 Characteristics

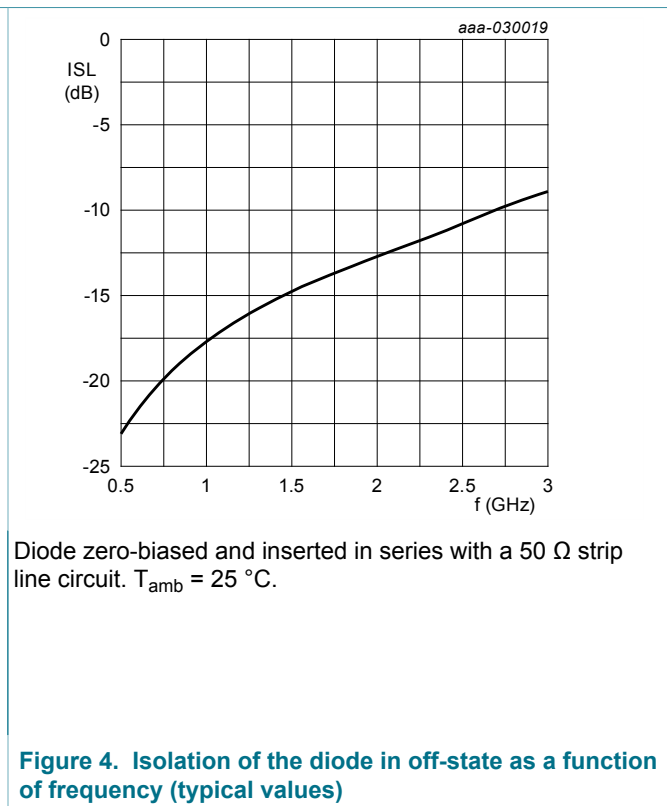
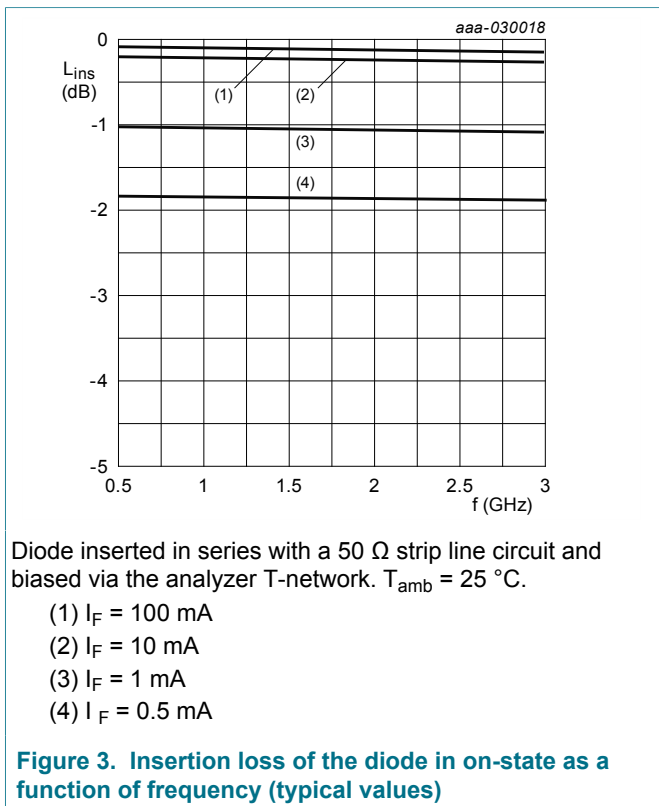
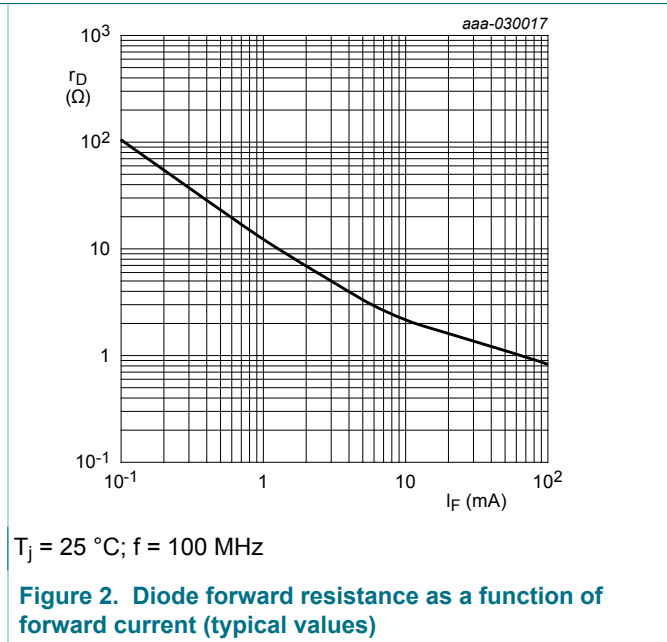
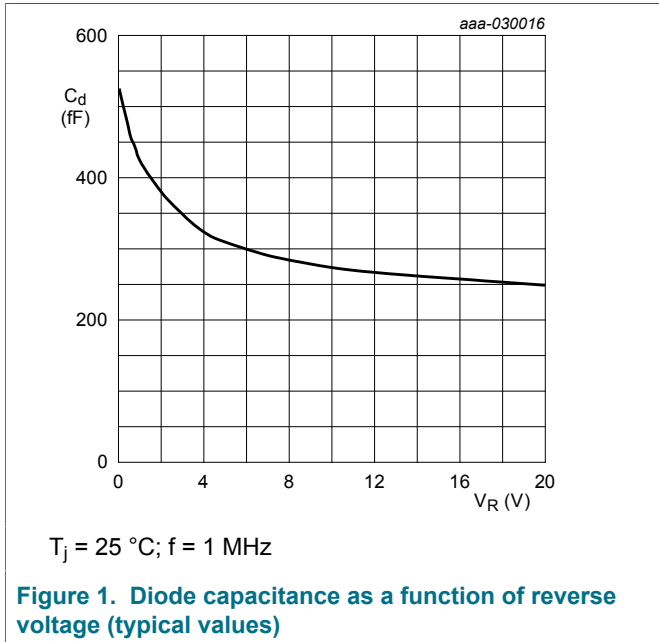
**Table 6. Characteristics**

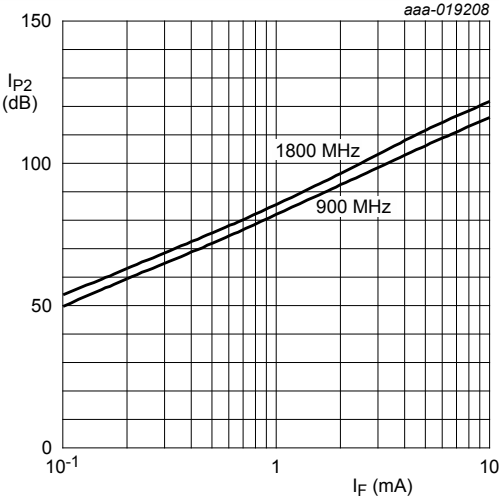
$T_j = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$V_F$	forward voltage	$I_F = 50\text{ mA}$	-	0.95	1.1	V	
$I_R$	reverse current	$V_R = 60\text{ V}$	-	-	10	$\mu\text{A}$	
		$V_R = 20\text{ V}$	-	-	1	$\mu\text{A}$	
$C_d$	diode capacitance	f = 1 MHz (see <a href="#">Figure 1</a> )					
		$V_R = 0\text{ V}$	-	0.52	-	pF	
		$V_R = 1\text{ V}$	-	0.37	-	pF	
		$V_R = 20\text{ V}$	-	0.23	0.35	pF	
$r_D$	diode forward resistance	f = 100 MHz (see <a href="#">Figure 2</a> )					
		$I_F = 0.5\text{ mA}$	[1]	-	20	40	$\Omega$
		$I_F = 1\text{ mA}$	[1]	-	10	20	$\Omega$
		$I_F = 10\text{ mA}$	[1]	-	2	3.8	$\Omega$
		$I_F = 100\text{ mA}$	[1]	-	0.7	1.35	$\Omega$
$\tau_L$	charge carrier life time	when switched from $I_F = 10\text{ mA}$ to $I_R = 6\text{ mA}$ ; $R_L = 100\ \Omega$ ; measured at $I_R = 3\text{ mA}$	-	1.55	-	$\mu\text{s}$	
$L_S$	series inductance	$I_F = 10\text{ mA}$ ; f = 100 MHz	-	1.6	-	nH	

[1] Guaranteed on AQL basis; inspection level S4, AQL 1.0

**8 Graphical data**





T<sub>amb</sub> = 25 °C

Figure 5. Second order intercept point as function of forward current; typical values

**9 Package outline**

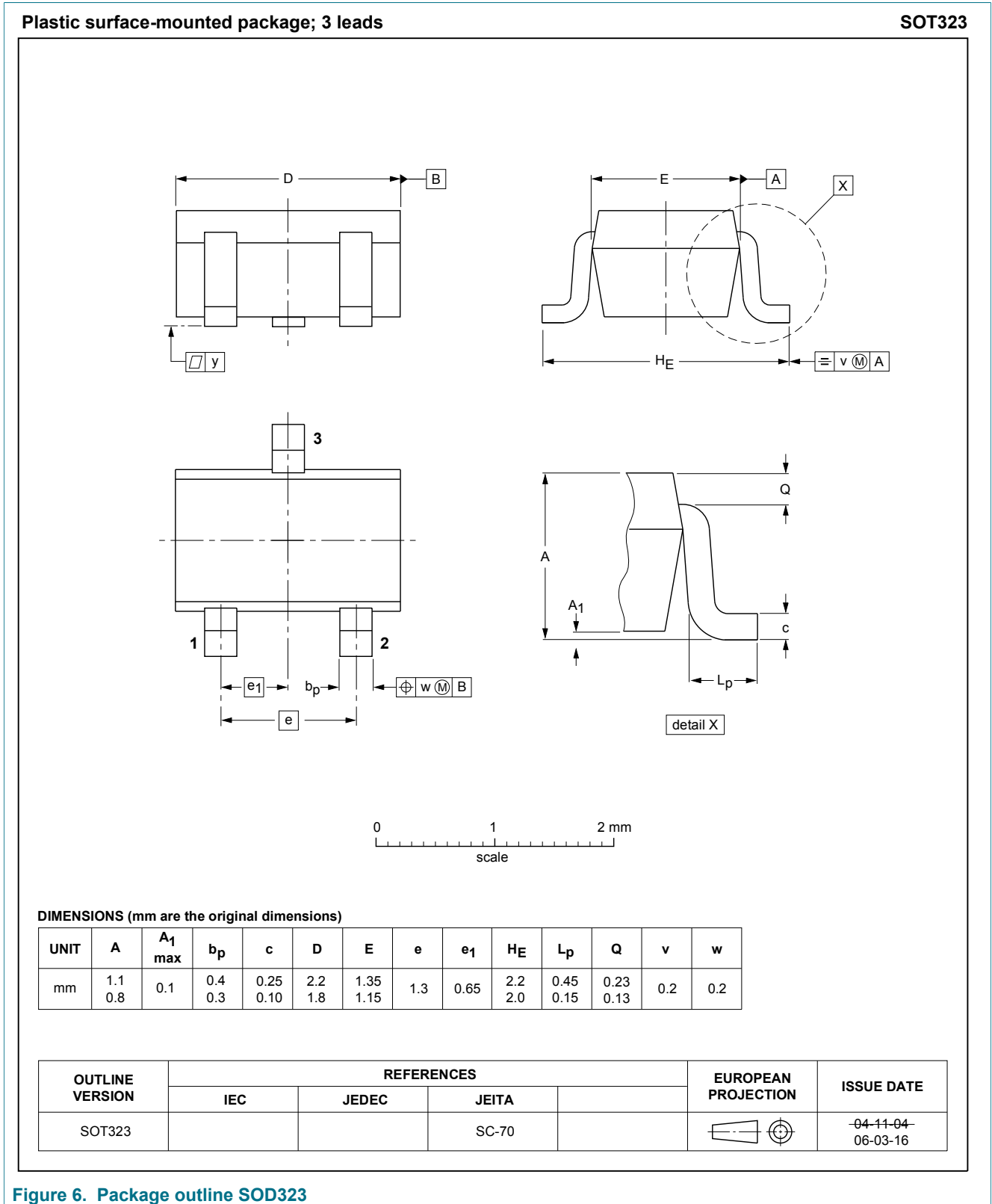


Figure 6. Package outline SOT323

## 10 Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP64-04W v.4.1	20190211	Product data sheet	-	BAP64-04W v.4
Modifications:	• changed condition for reverse current for $V_R$ from 175 V to 60 V			
BAP64-04W v.4	20181213	Product data sheet	-	BAP64-04W v.3
Modifications:	• <a href="#">Section 1.2</a> "Features and benefits" has been updated. • The "Legal information" pages have been updated.			
BAP64-04W v.3	20010129	Product data sheet	-	BAP64-04W v.2



## 11 Legal information

### 11.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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